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182734-2

CONTACT REC HE14 COSI LOOSE P



AMPMODU HE 13/HE 14

TE Internal #: 182734-2

TE Internal Description: CONTACT REC HE14

COSI LOOSE P

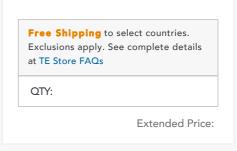
Contact Type : **Socket** Wire Size (AWG): 28 - 24 Wire Size (mm²): .08 - .24

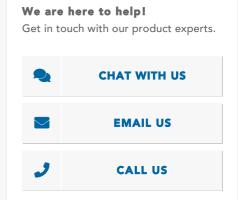
Contact Mating Area Plating Material: Tin

Packaging Method: Loose Piece

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Documents Features Product Compliance Product Drawings CONTACT REC HE14 COSI LOOSE P ▲ CONTACT REC HE14 COSI LOOSE P English CONTACT REC HE14 COSI LOOSE P

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3D PDF **CAD Files**

♣ 3D_CVM_CVM_182734-2_P1.pdf 3D

Customer View Model

L ENG_CVM_CVM_182734-2_P1.2d_dxf.zip

English

L ENG_CVM_CVM_182734-2_P1.3d_igs.zip

LNG_CVM_CVM_182734-2_P1.3d_stp.zip

English

Product Specifications **Application Specification**

LNG_SS_114-15104_A.pdf English

Product Environmental Compliance

TE Material Declaration

LENG_PC_MD_182734-2_A_MD_182734-

2_06092014732_dmtec.pdf English

Please review product documents or contact us for the latest agency approval information. Please Note: Use the Product Drawing for all design activity. Connector & Contact Terminates To: Wire & Cable Product Type Wire/Cable Type: Discrete Wire Features Product Type: Contact Contact Features Contact Base Material: Phosphor Bronze Contact Mating Area Plating Material Thickness (µm): 2.5 Contact Type : **Socket** Contact Mating Area Plating Material: Tin Termination Termination Method to Wire & Cable: Crimp, Insulation Displacement Crimp (IDC) Features **Dimensions** Accepts Wire Insulation Diameter Range: .8 - 1.5 mm [.032 - .059 in] Wire Size (AWG): 28 - 24 Wire Size (mm²): .08 - .24 Packaging Quantity: 200 Packaging Packaging Method: Loose Piece Features **EU RoHS** Directive 2011/65/EU This declaration covers EU Directive 2011/65/EU incl. Delegated Directive 2015/863/EU. The restrictions under 2015/863/EU apply as of 22 July 2021 for EEE categories 8 (medical devices) and 9 (monitoring and control equipment). **EU ELV Directive** 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016 **EU REACH** Current ECHA Candidate List: JUL 2019 (201) Regulation (EC) Candidate List Declared Against: JUL 2019 (201) No. 1907/2006 Halogen Content Solder Process Not applicable for solder process capability Capability

Statement of Compliance pdf

Statement of

Compliance

Compliance **Documents**

There may be Environmental Compliance related documents on the DOCUMENTATION Tab

Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidancedocuments/guidance-on-reach

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WIRE-TO-BOARD CONNECTOR..

182734-2 CONTACT REC HE14 COSI LOOSE



In-Stock From

Contact Type: Socket Wire Size: 28 - 24 AWG Wire Size : .08 - .24 mm² Contact Mating Area Plating

Material: Tin

Packaging Method: Loose Piece

WIRE-TO-BOARD CONNECTOR..

188744-1 CONTACT REC HE14 COSITIN **PLATED**



In-Stock From

Contact Type: Socket Wire Size: 28 - 24 AWG Wire Size : .08 - .24 mm² Contact Mating Area Plating Material: Tin

Packaging Method: Strip

WIRE-TO-BOARD CONNECTOR..

182734-3 CONTACT REC HE13 COSI LOOSE



In-Stock

Contact Type : Socket Wire Size: 28 - 24 AWG Wire Size : .08 - .24 mm² Contact Mating Area Plating Material: Gold

Packaging Method: Loose Piece

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WIRE-TO-BOARD CONNECTOR.

188746-1 CONTACT REC HE13 COSI GOLD PLATED



In-Stock From

Contact Type : Socket Wire Size : 28 - 24 AWG Wire Size : .08 - .24 mm² Contact Mating Area Plating

Material: Gold

Packaging Method: Strip



Multiple Configuration PCB Headers & Receptacles (85)



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